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PATENT

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Smith

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Salman Akram

Serial No.: 09/388,031

Filed: September 1, 1999

For: METALLIZATION STRUCTURES
FOR SEMICONDUCTOR DEVICE
INTERCONNECTS, METHODS FOR
MAKING SAME, AND
SEMICONDUCTOR DEVICES
INCLUDING SAME

Confirmation No.: 3303

Examiner: E. Lee

Group Art Unit: 2815
02/04/2003 ASHMITH 0000008 201469 09388031

01 FC:1201 Attorney Docket No.: 3442.2US (96-428)

CERTIFICATE OF MAILING

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AMENDMENT UNDER 37 C.F.R. §1.116

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Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Final Office Action mailed September 25, 2002, the three-month shortened statutory period for response to which expires on December 25, 2002. This response is submitted on or before three months from the mailing date of the Final Office Action, December 25, 2002 being a holiday.